



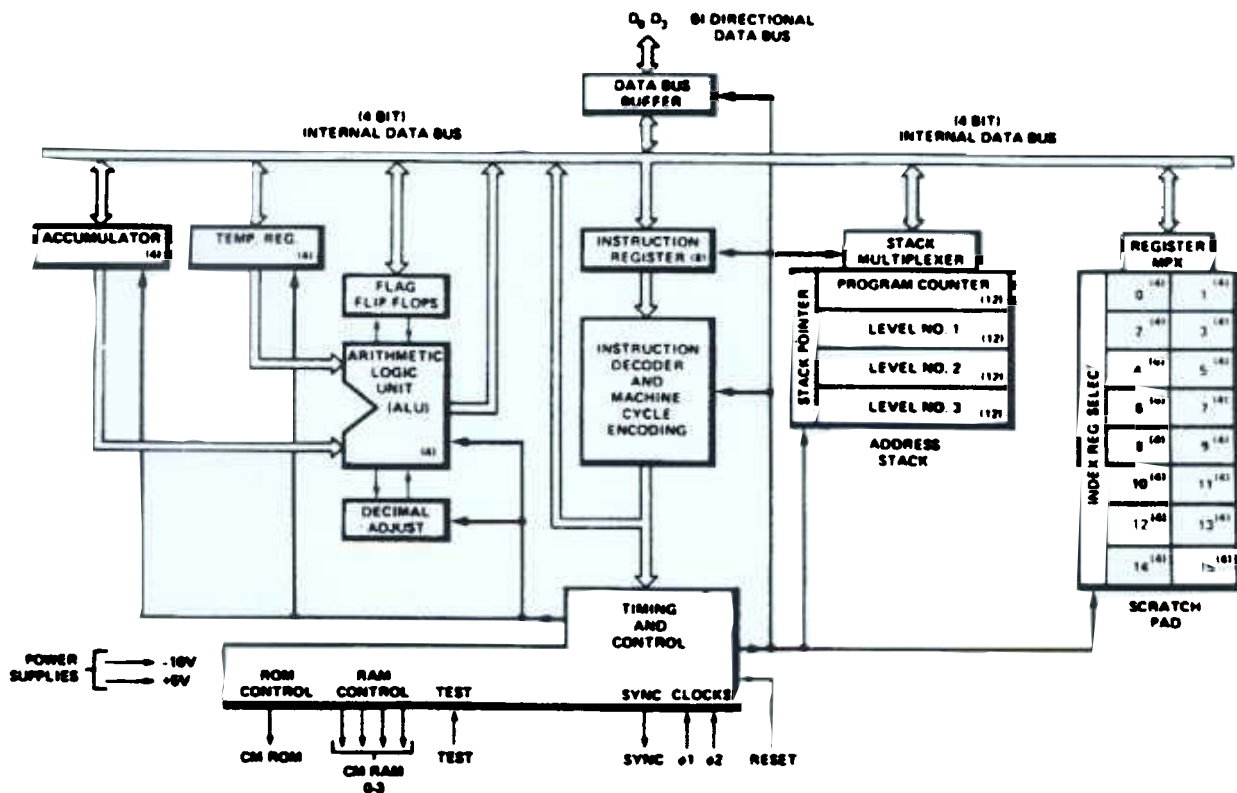
4004 SINGLE CHIP 4-BIT P-CHANNEL MICROPROCESSOR

- 4-Bit Parallel CPU With 46 Instructions
- Instruction Set Includes Conditional Branching, Jump to Subroutine and Indirect Fetching
- Binary and Decimal Arithmetic Modes
- 10.8 Microsecond Instruction Cycle
- CPU Directly Compatible With MCS-40 ROMs and RAMs
- Easy Expansion – One CPU can Directly Drive up to 32,768 Bits of ROM and up to 5120 Bits of RAM
- Standard Operating Temperature Range of 0° to 70° C
- Also Available With -40° to +85° C Operating Range

The Intel® 4004 is a complete 4-bit parallel central processing unit (CPU). The 4004 easily interfaces with keyboards, switches, displays, A-D converters, printers and other peripheral equipment.

The CPU can directly address 4K 8-bit instruction words of program memory and 5120 bits of data storage RAM. Sixteen index registers are provided for temporary data storage. Up to 16 4-bit input ports and 16 4-bit output ports may also be directly addressed.

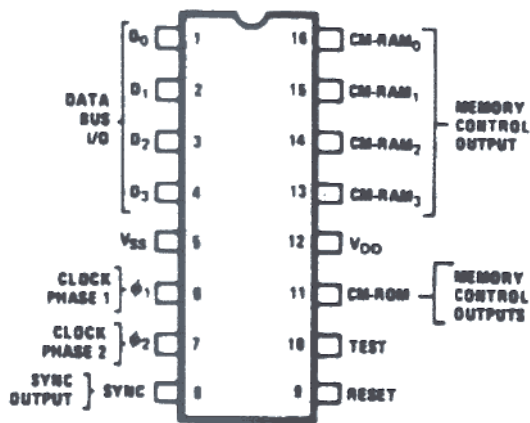
The 4004 is fabricated with P-channel silicon gate MOS technology.



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Pin Description



D₀-D₃

BIDIRECTIONAL DATA BUS. All address and data communication between the processor and the RAM and ROM chips occurs on these 4 lines.

RESET

RESET input. A logic "1" level at this input clears all flags and status registers and forces the program counter to zero. To completely clear all address and index registers, RESET must be applied for 64 clock cycles (8 machine cycles).

TEST

TEST input. The logical state of this signal may be tested with the JCN instruction.

SYNC

SYNC output. Synchronization signal generated by the processor and set to the ROM and RAM chips. It indicates the beginning of an instruction cycle.

CM-ROM

CM-ROM output. This is the ROM selection signal sent out by the processor when data is required from program memory.

CM-RAM₀ – CM-RAM₃

CM-RAM outputs. These are the bank selection signals for the 4002 RAM chips in the system.

φ₁, φ₂

Two phase clock inputs.

V_{SS}

Most positive voltage.

V_{DD}

V_{SS} -15 ±5% main supply voltage.

4004 Instruction Set

BASIC INSTRUCTIONS (* = 2 Word Instructions)

Hex Code	INSTRUCTION	OPR D ₇ D ₆ D ₅ D ₄	OPA D ₃ D ₂ D ₁ D ₀	DESCRIPTION OF OPERATION
00	NOP	0 0 0 0	0 0 0 0	No operation.
1 - ..	* JCN	0 0 0 1 A ₇ A ₆ A ₅ A ₄	C ₇ C ₆ C ₅ C ₄ A ₃ A ₂ A ₁ A ₀	Jump to ROM address A ₇ A ₆ A ₅ A ₄ A ₃ A ₂ A ₁ A ₀ (within the same ROM that contains this JCN instruction) if condition C ₇ C ₆ C ₅ C ₄ is true. otherwise go to the next instruction in sequence
2 - ..	* JIM	0 0 1 0 D ₇ D ₆ D ₅ D ₄	R R R 0 D ₃ D ₂ D ₁ D ₀	Fetch immediate (direct) from ROM Data D ₇ D ₆ D ₅ D ₄ D ₃ D ₂ D ₁ D ₀ to index register pair location RRR
3 -	FIN	0 0 1 1	R R R 0	Fetch indirect from ROM. Send contents of index register pair location 0 out as an address. Data fetched is placed into register pair location RRR.
3 -	JIN	0 0 1 1	R R R 1	Jump indirect. Send contents of register pair RRR out as an address at A ₇ and A ₆ time in the instruction cycle.
4 - ..	* JUN	0 1 0 0 A ₇ A ₆ A ₅ A ₄	A ₃ A ₂ A ₁ A ₀ A ₇ A ₆ A ₅ A ₄	Jump unconditional to ROM address A ₇ A ₆ A ₅ A ₄ A ₃ A ₂ A ₁ A ₀ .
5 - ..	* JMS	0 1 0 1 A ₇ A ₆ A ₅ A ₄	A ₃ A ₂ A ₁ A ₀ A ₇ A ₆ A ₅ A ₄	Jump to subroutine ROM address A ₇ A ₆ A ₅ A ₄ A ₃ A ₂ A ₁ A ₀ , save old address (up 1 level in stack)
6 -	INC	0 1 1 0	R R R R	Increment contents of register RRRR
7 - ..	* ISZ	0 1 1 1 A ₇ A ₆ A ₅ A ₄	R R R R A ₃ A ₂ A ₁ A ₀	Increment contents of register RRRR. Go to ROM address A ₇ A ₆ A ₅ A ₄ A ₃ A ₂ A ₁ A ₀ (within the same ROM that contains this ISZ instruction) if result ≠ 0. otherwise go to the next instruction in sequence
8 -	ADD	1 0 0 0	R R R R	Add contents of register RRRR to accumulator with carry
9 -	SUB	1 0 0 1	R R R R	Subtract contents of register RRRR to accumulator with borrow
A -	LD	1 0 1 0	R R R R	Load contents of register RRRR to accumulator
B -	XCH	1 0 1 1	R R R R	Exchange contents of index register RRRR and accumulator
C -	BBL	1 1 0 0	D D D D	Branch back (down 1 level in stack) and load data DDDD to accumulator
D -	LDM	1 1 0 1	D D D D	Load data DDDD to accumulator
FD	CLB	1 1 1 1	0 0 0 0	Clear both (Accumulator and carry)
F1	CLC	1 1 1 1	0 0 0 1	Clear carry.
F2	IAC	1 1 1 1	0 0 1 0	Increment accumulator.
F3	CMC	1 1 1 1	0 0 1 1	Complement carry.
F5	RAL	1 1 1 1	0 1 0 1	Rotate left (Accumulator and carry)
F6	RAR	1 1 1 1	0 1 1 0	Rotate right (Accumulator and carry)
F7	TCC	1 1 1 1	0 1 1 1	Transfer carry to accumulator and clear carry.
F8	DAC	1 1 1 1	1 0 0 0	Decrement accumulator
F9	TCS	1 1 1 1	1 0 0 1	Transfer carry subtract and clear carry
FA	STC	1 1 1 1	1 0 1 0	Set carry
FB	DAA	1 1 1 1	1 0 1 1	Decimal adjust accumulator
FC	KBP	1 1 1 1	1 1 0 0	Keyboard process. Converts the contents of the accumulator from a one out of four code to a binary code.
FD	DCL	1 1 1 1	1 1 0 1	Designate command line.

4001/4002/4008/4009/4289 INPUT/OUTPUT AND RAM INSTRUCTIONS

Hex Code	MNEMONIC	OPR D, D, D, D.	OPA D, D, D, D.	DESCRIPTION OF OPERATION
2	SRC	0 0 1 0	R R R 1	Send register control Send the address (contents of index register pair RRR) to ROM and RAM at X ₁ and X ₂ time in the instruction cycle
E0	WRM	1 1 1 0	0 0 0 0	Write the contents of the accumulator into the previously selected RAM main memory character
E1	WMP	1 1 1 0	0 0 0 1	Write the contents of the accumulator into the previously selected RAM output port (Output Lines)
E2	WRR	1 1 1 0	0 0 1 0	Write the contents of the accumulator into the previously selected ROM output port (I/O Lines)
E3	WPM	1 1 1 0	0 0 1 1	Write the contents of the accumulator into the previously selected half byte of read/write program memory (used with 4008/4009 or 4289 only)
E4	WR0	1 1 1 0	0 1 0 0	Write the contents of the accumulator into the previously selected RAM status character 0
E5	WR1	1 1 1 0	0 1 0 1	Write the contents of the accumulator into the previously selected RAM status character 1
E6	WR2	1 1 1 0	0 1 1 0	Write the contents of the accumulator into the previously selected RAM status character 2
E7	WR3	1 1 1 0	0 1 1 1	Write the contents of the accumulator into the previously selected RAM status character 3
E8	SBM	1 1 1 0	1 0 0 0	Subtract the previously selected RAM main memory character from accumulator with borrow
E9	RDM	1 1 1 0	1 0 0 1	Read the previously selected RAM main memory character into the accumulator
EA	ROR	1 1 1 0	1 0 1 0	Read the contents of the previously selected ROM input port into the accumulator (I/O Lines)
EB	ADM	1 1 1 0	1 0 1 1	Add the previously selected RAM main memory character to accumulator with carry
EC	RD0	1 1 1 0	1 1 0 0	Read the previously selected RAM status character 0 into accumulator
ED	RD1	1 1 1 0	1 1 0 1	Read the previously selected RAM status character 1 into accumulator
EE	RD2	1 1 1 0	1 1 1 0	Read the previously selected RAM status character 2 into accumulator
EF	RD3	1 1 1 0	1 1 1 1	Read the previously selected RAM status character 3 into accumulator

Hex	Mnemonic	Hex	Mnemonic	Hex	Mnemonic	Hex	Mnemonic
00	-	40	JUN	80	ADD 0	C0	BBL 0
01	-	41	JUN	81	ADD 1	C1	BBL 1
02	-	42	JUN	82	ADD 2	C2	BBL 2
03	-	43	JUN	83	ADD 3	C3	BBL 3
04	-	44	JUN	84	ADD 4	C4	BBL 4
05	-	45	JUN	85	ADD 5	C5	BBL 5
06	-	46	JUN	86	ADD 6	C6	BBL 6
07	-	47	JUN	87	ADD 7	C7	BBL 7
08	-	48	JUN	88	ADD 8	C8	BBL 8
09	-	49	JUN	89	ADD 9	C9	BBL 9
0A	-	4A	JUN	8A	ADD 10	CA	BBL 10
0B	-	4B	JUN	8B	ADD 11	CB	BBL 11
0C	-	4C	JUN	8C	ADD 12	CC	BBL 12
0D	-	4D	JUN	8D	ADD 13	CD	BBL 13
0E	-	4E	JUN	8E	ADD 14	CE	BBL 14
0F	-	4F	JUN	8F	ADD 15	CF	BBL 15
10	JCN CN=0	50	JMS	90	SUB 0	D0	LDM 0
11	JCN CN=1 also JNT	51	JMS	91	SUB 1	D1	LDM
12	JCN CN=2 also JC	52	JMS	92	SUB 2	D2	LDM 2
13	JCN CN=3	53	JMS	93	SUB 3	D3	LDM 3
14	JCN CN=4 also JZ	54	JMS	94	SUB 4	D4	LDM 4
15	JCN CN=5	55	JMS	95	SUB 5	D5	LDM 5
16	JCN CN=6	56	JMS	96	SUB 6	D6	LDM 6
17	JCN CN=7	57	JMS	97	SUB 7	D7	LDM 7
18	JCN CN=8	58	JMS	98	SUB 8	D8	LDM 8
19	JCN CN=9 also JT	59	JMS	99	SUB 9	D9	LDM 9
1A	JCN CN=10 also JNC	5A	JMS	9A	SUB 10	DA	LDM 10
1B	JCN CN=11	5B	JMS	9B	SUB 11	DB	LDM 11
1C	JCN CN=12 also JNZ	5C	JMS	9C	SUB 12	DC	LDM 12
1D	JCN CN=13	5D	JMS	9D	SUB 13	DD	LDM 13
1E	JCN CN=14	5E	JMS	9E	SUB 14	DE	LDM 14
1F	JCN CN=15	5F	JMS	9F	SUB 15	DF	LDM 15
20	FIM 0	60	INC 0	A0	LD 0	E0	WRM
21	SRC 0	61	INC 1	A1	LD 1	E1	WMP
22	FIM 2	62	INC 2	A2	LD 2	E2	WRR
23	SRC 2	63	INC 3	A3	LD 3	E3	WPM
24	FIM 4	64	INC 4	A4	LD 4	E4	WRO
25	SRC 4	65	INC 5	A5	LD 5	E5	WR1
26	FIM 6	66	INC 6	A6	LD 6	E6	WR2
27	SRC 6	67	INC 7	A7	LD 7	E7	WR3
28	FIM 8	68	INC 8	A8	LD 8	E8	SBM
29	SRC 8	69	INC 9	A9	LD 9	E9	RODM
2A	FIM 10	6A	INC 10	AA	LD 10	EA	RDR
2B	SRC 10	6B	INC 11	AB	LD 11	EB	ADM
2C	FIM 12	6C	INC 12	AC	LD 12	EC	RDO
2D	SRC 12	6D	INC 13	AD	LD 13	ED	RO1
2E	FIM 14	6E	INC 14	AE	LD 14	EE	RO2
2F	SRC 14	6F	INC 15	AF	LD 15	EF	RO3
30	FIN 0	70	ISZ 0	B0	XCH 0	F0	CLB
31	JIN 0	71	ISZ 1	B1	XCH 1	F1	CLC
32	FIN 2	72	ISZ 2	B2	XCH 2	F2	IAC
33	JIN 2	73	ISZ 3	B3	XCH 3	F3	CMC
34	FIN 4	74	ISZ 4	B4	XCH 4	F4	CMA
35	JIN 4	75	ISZ 5	B5	XCH 5	F5	RAL
36	FIN 6	76	ISZ 6	B6	XCH 6	F6	RAR
37	JIN 6	77	ISZ 7	B7	XCH 7	F7	TCC
38	FIN 8	78	ISZ 8	B8	XCH 8	F8	DAC
39	JIN 8	79	ISZ 9	B9	XCH 9	F9	TCS
3A	FIN 10	7A	ISZ 10	BA	XCH 10	FA	STC
3B	JIN 10	7B	ISZ 11	BB	XCH 11	FB	DAA
3C	FIN 12	7C	ISZ 12	BC	XCH 12	FC	KBP
3D	JIN 12	7D	ISZ 13	BD	XCH 13	FD	DCL
3E	FIN 14	7E	ISZ 14	BE	XCH 14	FE	-
3F	JIN 14	7F	ISZ 15	BF	XCH 15	FF	-

Second hex
digit is part
of jump
address.

Absolute Maximum Ratings*

Ambient Temperature Under Bias
Storage Temperature
Input Voltages and Supply Voltage
with respect to V_{SS}
Power Dissipation

..... 0°C to 70°C
-55°C to + 125°C
+0.5V to -20V
..... 1.0 Watt

*COMMENT:

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

D.C. and Operating Characteristics

T_A = 0°C to 70°C; V_{SS} - V_{DD} = 15V ± 5%; t_{APW} = t_{AD1} = 400 nsec; logic "0" is defined as the more positive voltage (V_{IH}, V_{OH}); logic "1" is defined as the more negative voltage (V_{IL}, V_{OL}); Unless Otherwise Specified.

SUPPLY CURRENT

Symbol	Parameter	Min.	Limit Typ.	Max.	Unit	Test Conditions
I _{DD}	Average Supply Current		30	40	mA	T _A = 25°C

INPUT CHARACTERISTICS

I _{LI}	Input Leakage Current		10	μA	V _{IL} = V _{DD}
V _{IH}	Input High Voltage (Except Clocks)	V _{SS} - 1.5		V _{SS} + 3	V
V _{IL}	Input Low Voltage (Except Clocks)	V _{DD}		V _{SS} - 5.5	V
V _{ILO}	Input Low Voltage	V _{DD}		V _{SS} - 4.2	V
V _{IHC}	Input High Voltage Clocks	V _{SS} - 1.5		V _{SS} + 3	V
V _{ILC}	Input Low Voltage Clocks	V _{DD}		V _{SS} - 13.4	V

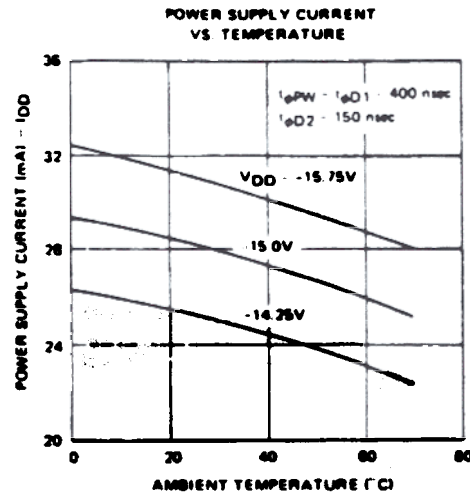
OUTPUT CHARACTERISTICS

I _{LO}	Data Bus Output Leakage Current		10	μA	V _{OUT} = -12V
V _{OH}	Output High Voltage	V _{SS} - .5V	V _{SS}	V	Capacitance Load
I _{OL}	Data Lines Sinking Current	8	15	mA	V _{OUT} = V _{SS}
I _{OL}	CM-ROM Sinking Current	6.5	12	mA	V _{OUT} = V _{SS}
I _{OL}	CM-RAM Sinking Current	2.5	6	mA	V _{OUT} = V _{SS}
V _{OL}	Output Low Voltage, Data Bus, CM, SYNC	V _{SS} - 12		V _{SS} - 6.5	V
R _{OH}	Output Resistance, Data Line "0" Level		150	250	Ω
R _{OH}	CM-ROM Output Resistance, Data Line "0" Level		320	600	Ω
R _{OH}	CM-RAM Output Resistance, Data Line "0" Level		1.1	1.8	kΩ

CAPACITANCE

C _φ	Clock Capacitance		14	20	pF
C _{DB}	Data Bus Capacitance		7	10	pF
C _{IN}	Input Capacitance			10	pF
C _{OUT}	Output Capacitance			10	pF

Typical D.C. Characteristics



A.C. Characteristics

 $T_A = 0^\circ\text{C to } 70^\circ\text{C}$, $V_{SS} - V_{DD} = 15\text{V} \pm 5\%$

Symbol	Parameter	Min.	Limit Typ.	Max.	Unit	Test Conditions
t_{CY}	Clock Period	1.35		2.0	μsec	
t_{pR}	Clock Rise Time			50	ns	
t_{pF}	Clock Fall Times			50	ns	
	Clock Width	380		480	ns	
	Clock Delay ϕ_1 to ϕ_2	400		550	ns	
	Clock Delay ϕ_2 to ϕ_1	150			ns	
	Data-In, CM, SYNC Write Time	350	100		ns	
	Data-In, CM, SYNC Hold Time	40	20		ns	
	Data Bus Hold Time During M_2 - X_1 and and X_2 - X_3 Transition.	150			ns	
$t_{OS[2]}$	Set Time (Reference)	0			ns	
	Data-Out Access Time					$C_{OUT} =$ 500pF Data Lines
	Data Lines			930	ns	200pF Data Lines ⁽⁴⁾
	Data Lines			700	ns	500pF SYNC
	SYNC			930	ns	180pF CM-ROM
	CM-ROM			930	ns	50pF CM-RAM
	CM-RAM			930	ns	$C_{OUT} = 20\text{pF}$
t_{OH}	Data-Out Hold Time	50	150		ns	

Notes: 1. t_H measured with $t_{pR} = 10\text{nsec}$.

2. T_{ACC} is Data Bus, SYNC and CM-line output access time referred to the ϕ_2 trailing edge which clocks these lines out. t_{OS} is the same output access time referred to the leading edge of the next ϕ_2 clock pulse.

3. All MCS-40 components which may transmit instruction or data to the 4004 at M_2 and X_2 always enter a float state until the 4004 takes over the data bus at X_1 and X_3 time. Therefore the t_H requirement is always insured since each component contributes 10 μA of leakage current and 10pF of capacitance which guarantees that the data bus cannot change faster than 1V/ μs .

4. $C_{DATA\ BUS} = 200\text{pF}$ if 4008 and 4009 or 4289 is used.

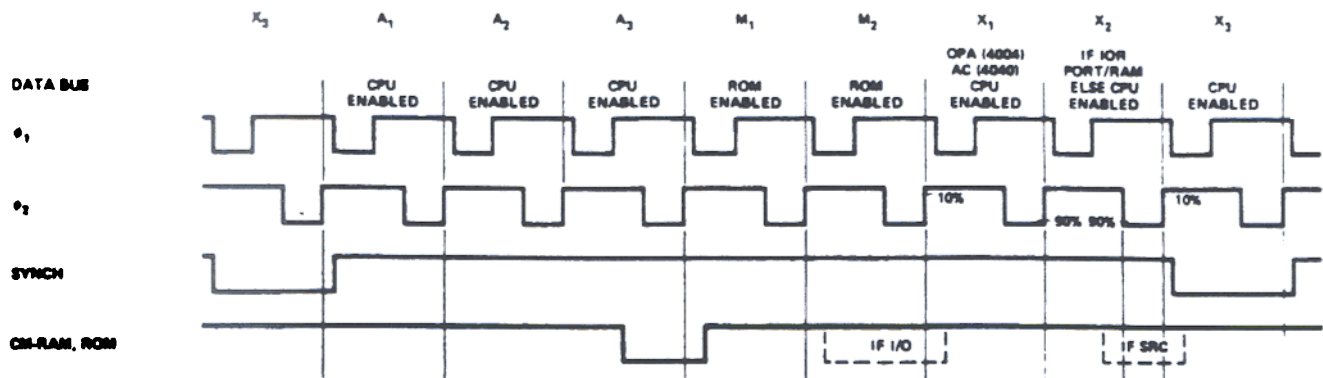


Figure 1. Timing Diagram.

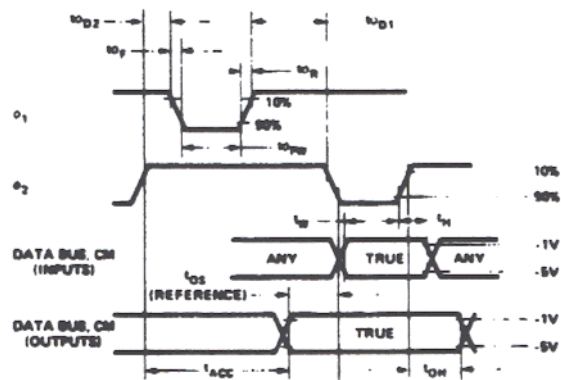


Figure 2. Timing Detail.